



Appl. No. 09/806,401  
Amdt. Dated February 26, 2004  
Reply to Office Action of August 26, 2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Harry Hedler *et al.*  
Application No. : 09/806,401  
Filed : 10/22/2001  
Title : ELECTRONIC MODULE, ESPECIALLY A MULTICHIP  
MODULE, WITH MULTI-LAYER METALLIZATION AND  
CORRESPONDING PRODUCTION METHOD  
Group/Art Unit : 2827  
Examiner : David E. Graybill  
Docket No. : KSN0012

M/S FEE AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT**

Sir:

In response to the Office Action of August 26, 2003, please amend the above-identified application as follows.

**Amendments to the Claims** are reflected in the listing of claims, which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 4 of this paper.